2SB1416

Silicon PNP epitaxial planar type

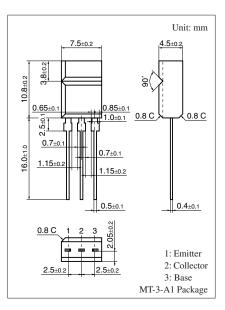
For low-frequency power amplification Complementary to 2SD2136

Features

- \bullet High forward current transfer ratio h_{FE} which has satisfactory linearity
- \bullet Low collector-emitter saturation voltage $V_{\mbox{CE(sat)}}$
- Allowing automatic insertion with radial taping

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit			
Collector-base voltage (Emitter open)	V _{CBO}	V _{CBO} -60				
Collector-emitter voltage (Base open)	V _{CEO}	-60	V			
Emitter-base voltage (Collector open)	V _{EBO}	-5	V			
Collector current	I _C	-3	А			
Peak collector current	I _{CP}	-5	А			
Collector power dissipation	P _C	1.5	W			
Junction temperature	Tj	150	°C			
Storage temperature	T _{stg}	-55 to +150	°C			



Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

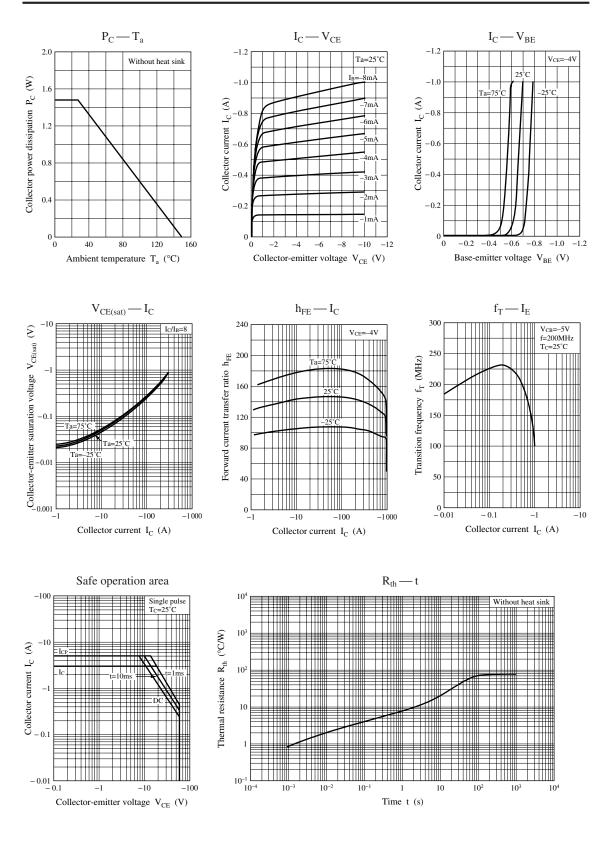
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = -30 \text{ mA}, I_{\rm B} = 0$	-60			V
Base-emitter voltage	V _{BE}	$V_{CE} = -4 V, I_C = -3 A$			-1.8	V
Collector-emitter cutoff current (E-B short)	I _{CES}	$V_{CE} = -60 \text{ V}, V_{BE} = 0$			-200	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = -30 \text{ V}, I_B = 0$			-300	μΑ
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = -5 V, I_C = 0$			-1	mA
Forward current transfer ratio	h _{FE1} *	$V_{CE} = -4 V, I_C = -1 A$	40		250	_
	h _{FE2}	$V_{CE} = -4 V, I_C = -3 A$	10			
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -3$ A, $I_{\rm B} = -0.375$ A			-1.2	V
Transition frequency	f _T	$V_{CB} = -5 \text{ V}, I_E = 0.1 \text{ A}, f = 200 \text{ MHz}$		270		MHz
Turn-on time	t _{on}	$I_C = -1 A, I_{B1} = -0.1 A, I_{B2} = 0.1 A$		0.5		μs
Storage time	t _{stg}			1.2		μs
Fall time	t _f			0.3		μs

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Р	Q	R
h _{FE1}	40 to 90	70 to 150	120 to 250

Panasonic



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